

D-Band Sub-Harmonic Mixer

RF:110-170 GHz/LO:55-85 GHz/IF:DC-30 GHz

TLHM-110170-0230-06

TLHM-110170-0220-06 is a D-Band Sub-Harmonic mixer. The mixer supports the full waveguide band operation for LO frequency from 55 to 85 GHz and RF frequency from 110 to 170 GHz with an extremely broad IF output from DC to 30 GHz. The mixer offers a conversion loss of 11 dB typical@IF=322.5MHz and LO input power of 10dBm typical.

Features:

- Low LO Power Requirement
- Subharmonic Mixing
- Compact Package

Applications:

- Radar Systems
- Communication Systems
- Test Equipment

电气特性 Electrical Characteristics:

参数 Parameter	Min	Typ	Max	单位 Units
RF频率 RF Frequency	110		170	GHz
LO频率 LO Frequency	55		85	GHz
IF频率 IF Frequency	DC		30	GHz
LO 驱动功率 LO-Input power		10		dBm
单边带变频损耗 SSB Conversion Loss@IF=322.5MHz		-11		dB
单边带变频损耗 SSB Conversion Loss@LO=55GHz		-12		dB

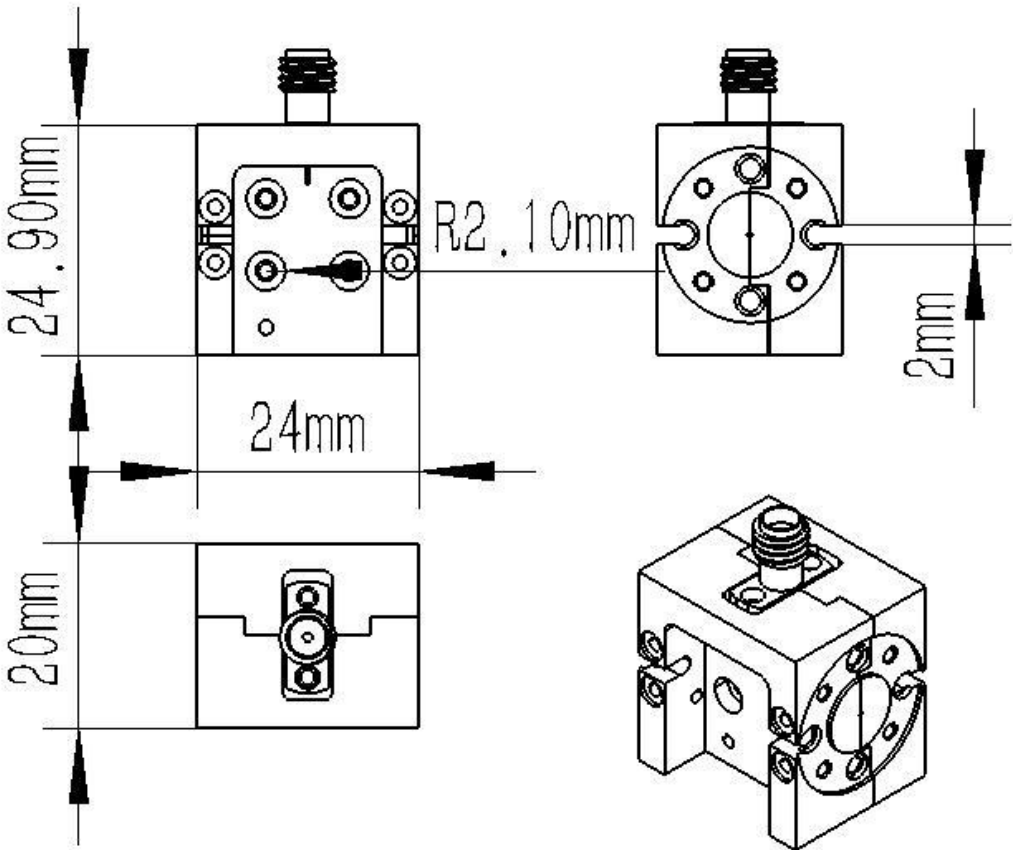
机械特性 Mechanical Specifications:

参数 Parameter	指标 Value	单位 Units
RF 接口RF Connector	WR-06/UG-387/U	
LO 接口LO Connector	WR-12/UG-387/U	
IF 接口 IF Connector	2.92mm Female	
尺寸 Size	24*24.9*20	mm

绝对最大值 Absolute Maximum Ratings:

参数 Parameter	指标 Value
RF 功率 RF Input Power	6 dBm
ESD灵敏度 ESD sensitivity (HBm)	Class 0, passed 150V

外形图 Outline Drawing: Unit:mm



温度环境 Environmental Conditions:

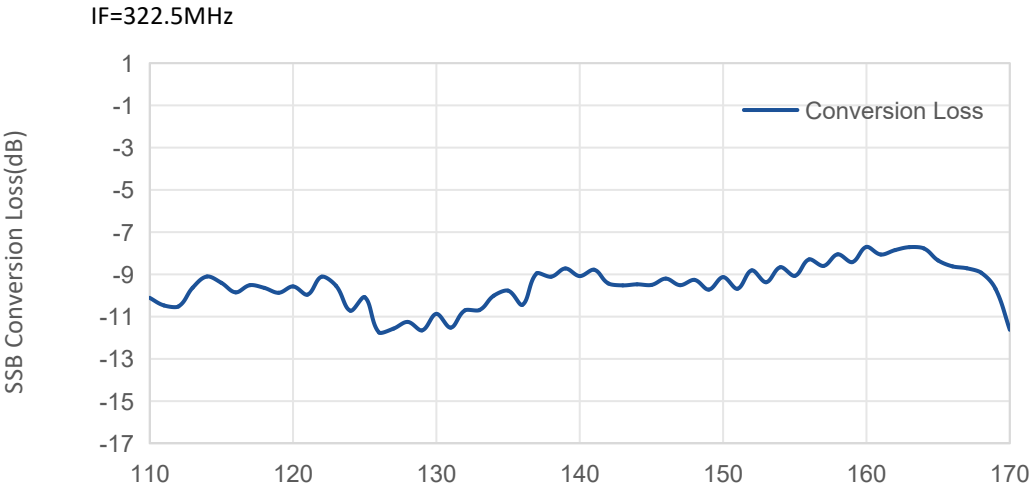
参数 Parameter	Min	Typ	Max	单位 Units
操作温度 Operating Temperature	-10		+65	℃
存储温度 Non-operating Temperature	-45		+85	℃
相对湿度 Relative humidity		95		%
海拔 Altitude	10,000			feet
震动 Shock / Vibration(MIL-STD-810F)	25g rms (15 degree 2KHz) endurance, 1 hour per axis			
冲击 Shock(non operating)	20G for 11msc half sin wave,3 axis both directions			

订货信息 Ordering Information:

标准型号 Base Number	描述 Desciption	版本号 Revision
TURHM-110170023006	D-Band Sub-Harmonic Mixer RF:110-170GHz,LO:55-85GHz,IF:DC-30GHz	Rev.1.1

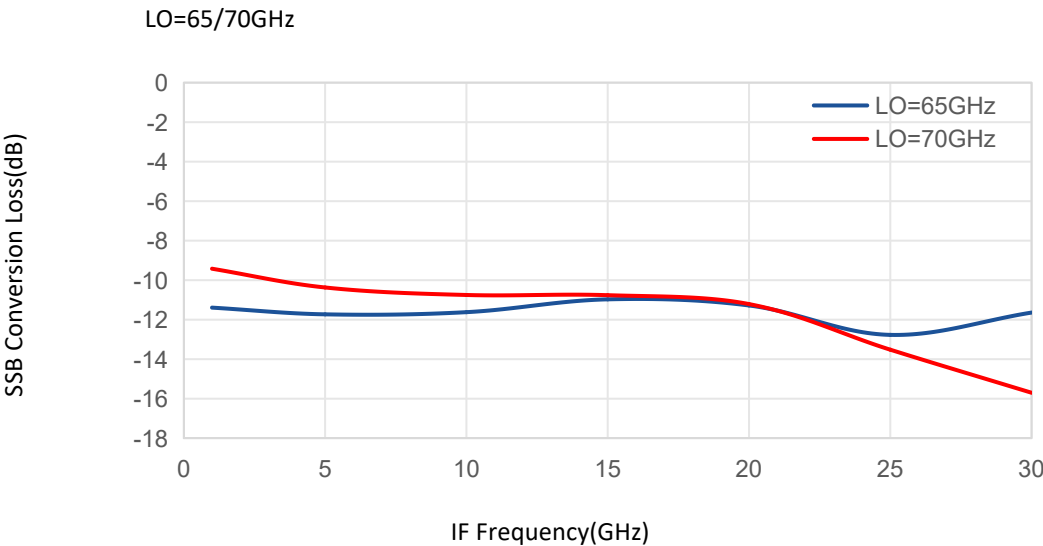
典型曲线 Typical Performance Data:

SSB Conversion Loss vs RF Frequency



典型曲线 Typical Performance Data:

SSB Conversion Loss vs RF Frequency



Note: Above data is for ref only, actual data may vary from unit to unit depending on operating environment and other factors like material lots etc.